TMS2018

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14TH ANNUAL ADVANCED MICROELECTRONIC PACKAGING, EMERGING INTERCONNECTION TECHNOLOGY, AND LEAD-FREE SOLDER WORKSHOP

SUNDAY, MARCH 11, 2018 • 8:30 A.M. TO 4:30 P.M.

Continuing advances in microelectronic, optoelectronic, and nanoelectronic devices require new materials and technologies to meet the increasing electrical, thermal, mechanical, reliability, performance, and environmental demands placed on interconnects and packaging at all levels. This workshop will address current research and discuss opportunities and development trends in packaging materials and process, including lead-free solder, alternative interconnects, conductive adhesive, epoxy, substrates, 3D packaging, wafer level packing, quality, reliability, and failure analysis.

INSTRUCTORS

Deepak Goyal, Intel
Sangil Lee, Invensas Corporation
Yan Li, Intel
Kwang-Lung Lin, National Cheng Kung University
Pilin Liu, Intel
Ravi Mahajan, Intel
Panat Rahul, Washington State University
Minfeng Yu, Georgia Institute of Technology

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TMS Functional Materials Division; Electronic Packaging and Interconnection Materials Committee

REGISTRATION FEES

	Advanced	On-Site
Member	$175	$225
Non-member	$225	$275
Student	$75	$125

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